

# AST-S200T

## Infrared Table Top Microscope System

The AST-S200T is used for sub-surface observation, imaging, verification and inspection of materials. Transparent to the Near Infrared (NIR) / Shortwave Infrared (SWIR) wavelengths.

### CAPABILITY

#### **Metrology:**

- Overlay alignment measurement and verification
- Die alignment measurement and verification, (flip chip/hybridization)
- Sub-surface feature based measurements
- Aperture measurements
- Thickness measurements based on focus adjust Z axis readout

#### **Inspection:**

- MEMS device inspection
- 3D Stacking process development and control
- Incoming wafer inspection
- Photovoltaic inspection
- Wafer level CSP's

#### **QA/Reliability/R&D:**

- Facilitates continuous improvements for development and production

### FLEXIBILITY

#### **Accessories:**

- Variety of optical, digital, illumination, polarizer/ analyzer and wavelength filter accessories available for application optimization

#### **Fixtures:**

- Custom wafer and device fixtures

### SCALABILITY

#### **Manual to Automation:**

- Scalable from manual to high throughput automation systems

### POWERFUL

#### **Effectiveness:**

- Able to penetrate thicker, more highly doped materials with rougher surfaces than other systems

#### **Digital Readout:**

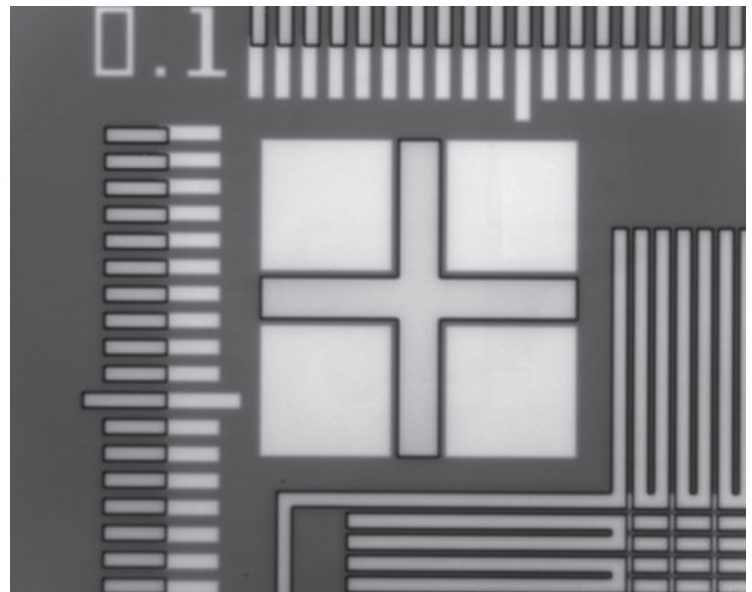
- Integrated digital readout with XYZ coordinates

#### **Design:**

- Coarse/fine manual operation with optional motorized XYZ joystick control



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#### **Precise:**

- Submicron-precision optical measurements
- Precision staging, to 0.1 micron linear encoder resolution
- Highest resolution 900-1700nm InGaAs digital camera in class

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## OPTICAL SPECIFICATIONS

### Camera:

- Cooled InGaAs (900-1700nm)
- Silicon-based option for NIR applications, (740nm-1100nm)

### Illumination:

- Epi, optimized Koehler
- Transmitted, optimized sub-stage

### Filters:

- Multi position filter slider sets available based on application

### Aperture/Field Diaphragms:

- Manual adjust

### Magnification:

- 10x-1000x

### Objectives:

- 1x-100x, (1x, 2.5x, 5x, 10x, 20x, 50x, 100x). Greater than 100x objectives are available based on the application

### Turret:

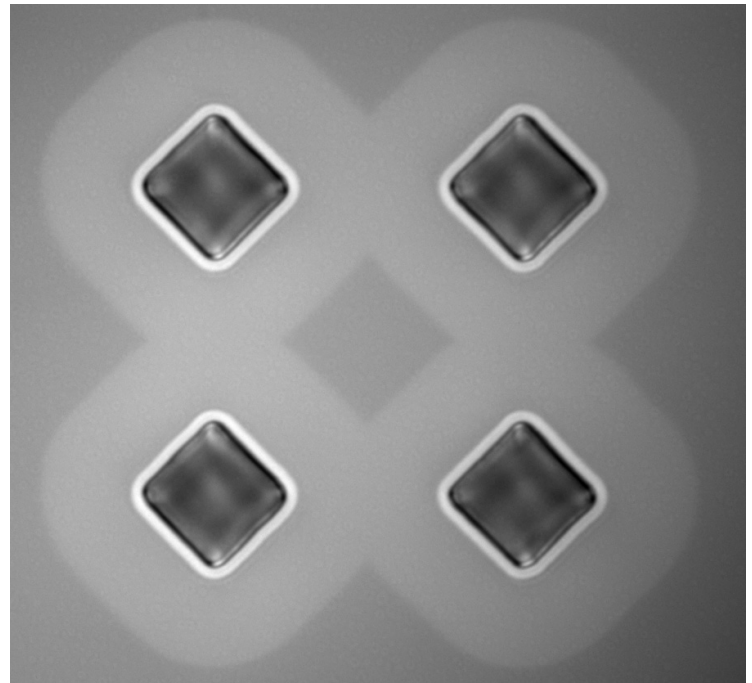
- Manual, optional motorized

### Resolution:

- Submicron optical and digital

### Display:

- Large monitor for live and stored image display



Multi-Layer Alignment

## PLATFORM SPECIFICATIONS

### Stand:

- 8" Microscope stand with coarse/fine Z focus control

### Stage:

- 8" x 8" Stage with coarse/fine manual position control. Other stage sizes available upon request.
- Optional motorized stage with joystick control available

## PROCESS

### In Process:

- Verification of critical alignment applications such as: MEMS, wafer bonding, 3D chip stacking, crack/chip inspection metrology.

### Post Process:

- Verification, validation, inspection and measurement of critical sub-surface features

### Failure Analysis:

- Process development tool verification, part characterization, qualification and environmental testing.

